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(12) **United States Design Patent** (10) **Patent No.:** **US D965,531 S**
Rudaitis et al. (45) **Date of Patent:** **** Oct. 4, 2022**

(54) **CONNECTOR HOUSING**
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OH (US)

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(**) Term: **15 Years**

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(21) Appl. No.: **29/810,050**

Balluff I/O device, downloaded image from Internet on Jul. 17,
2018 From: <http://www.directindustry.com/prod/balluff/product-7415-1345339.html>.

(22) Filed: **Sep. 30, 2021**

(Continued)

Related U.S. Application Data

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17, 2018, now Pat. No. Des. 934,811.

Primary Examiner — Shawn T Gingrich

(51) **LOC (13) Cl.** **13-03**

(74) *Attorney, Agent, or Firm* — Renner, Otto, Boisselle
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(52) **U.S. Cl.**
USPC **D13/147**

(57) **CLAIM**

(58) **Field of Classification Search**
USPC D13/110, 112, 118, 123, 146, 147,
D13/158-160, 173, 174, 177, 178, 184,
D13/199, 133, 149, 153, 154
CPC G05B 19/04; G05B 19/41; G06F 13/20;
G08B 5/36; H01R 9/24; H05K 7/00;
H05K 7/14; H04L 12/24; H04L 12/40
See application file for complete search history.

The ornamental design for connector housing, as shown and
described.

DESCRIPTION

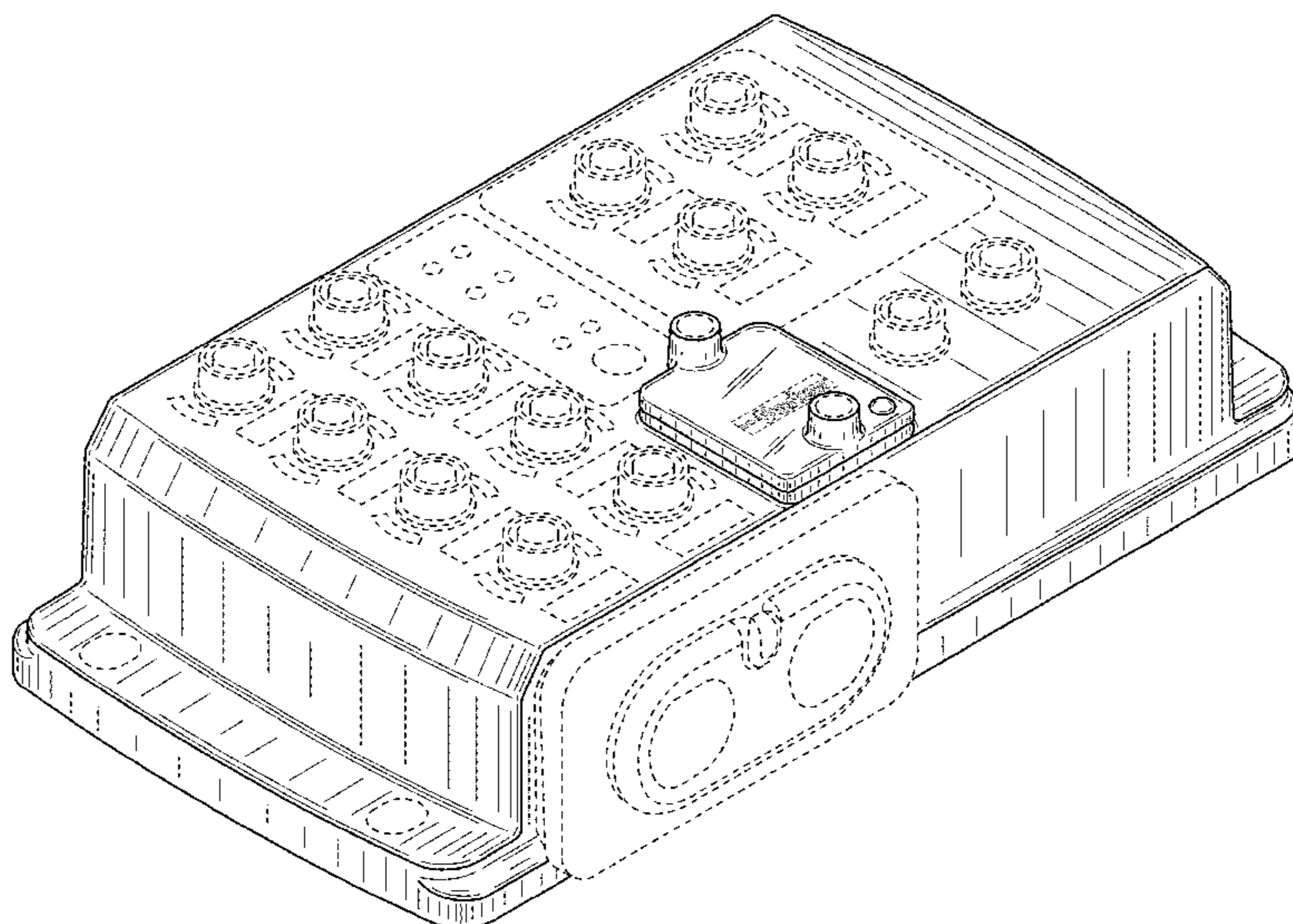
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FIG. 1 is a perspective view of an embodiment of a
connector housing showing our new design;
FIG. 2 is a top plan side view thereof;
FIG. 3 is a bottom plan view thereof;
FIG. 4 is a front elevational view thereof;
FIG. 5 is a rear elevation view thereof;
FIG. 6 is a left side elevational view thereof; and,
FIG. 7 is a right side elevational view thereof.
The broken lines in the drawings illustrate portions of the
article and form no part of the claimed design.

1 Claim, 5 Drawing Sheets



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Turck IO device, downloaded image from Internet on Jul. 17, 2018
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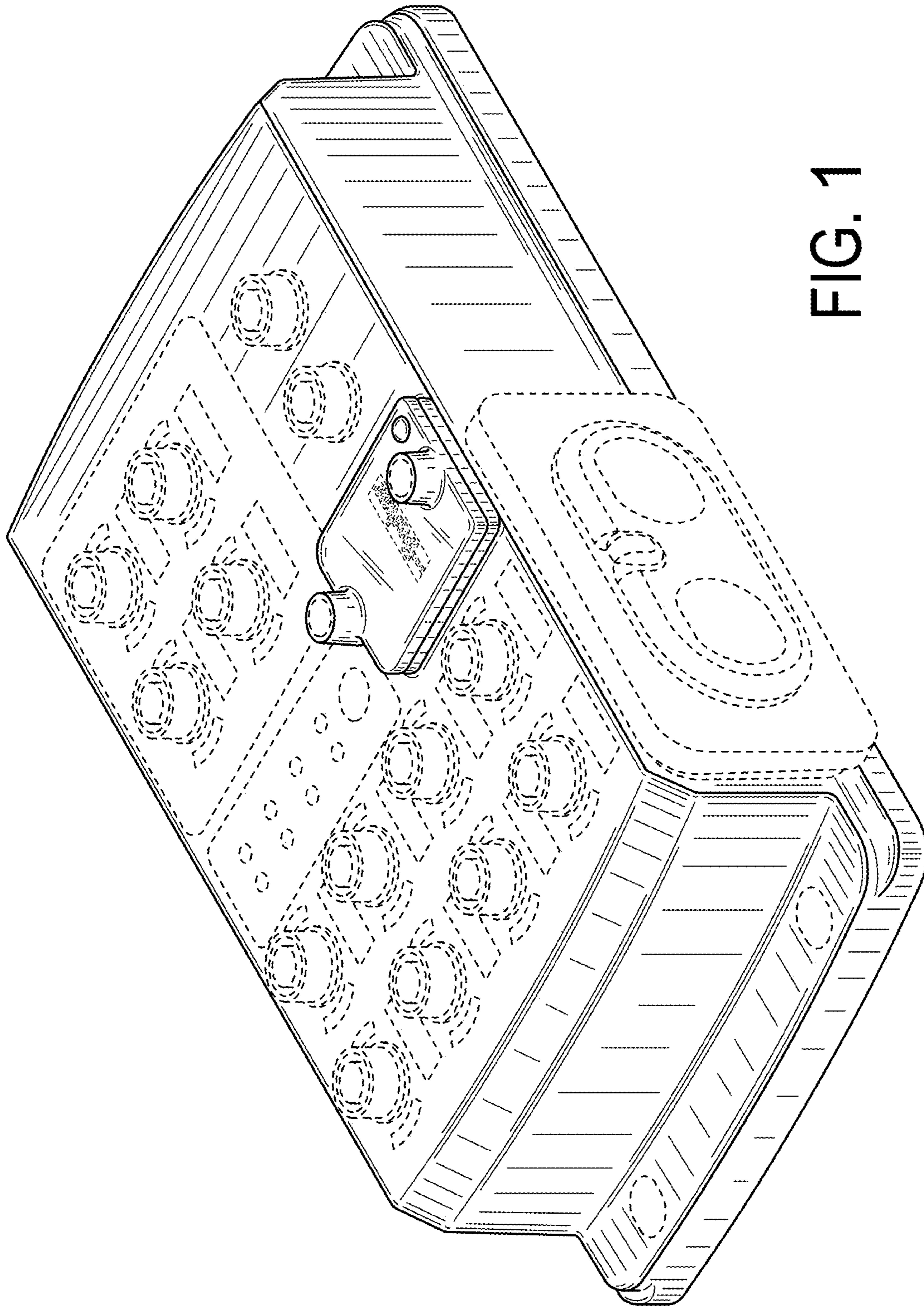


FIG. 1

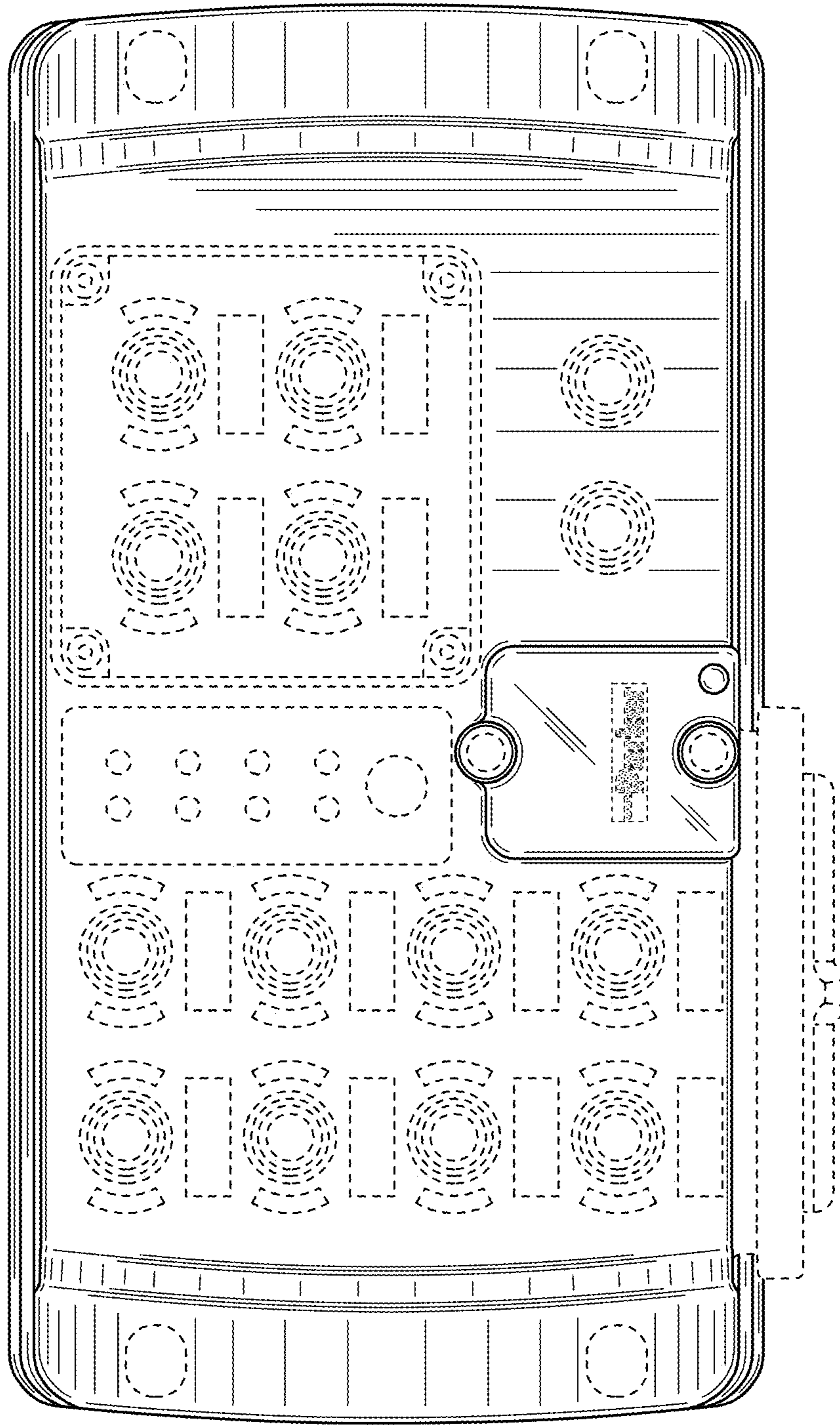


FIG. 2

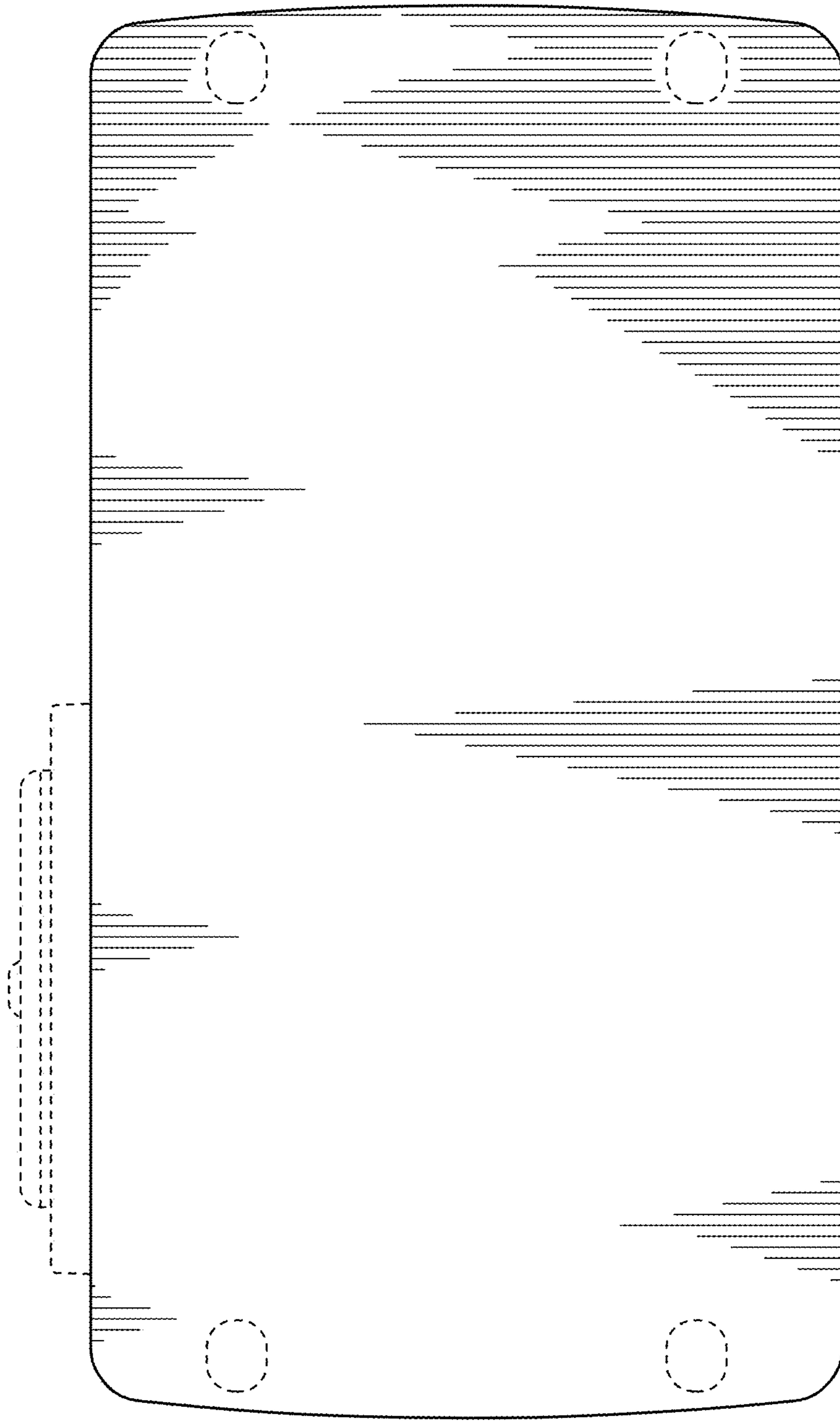


FIG. 3

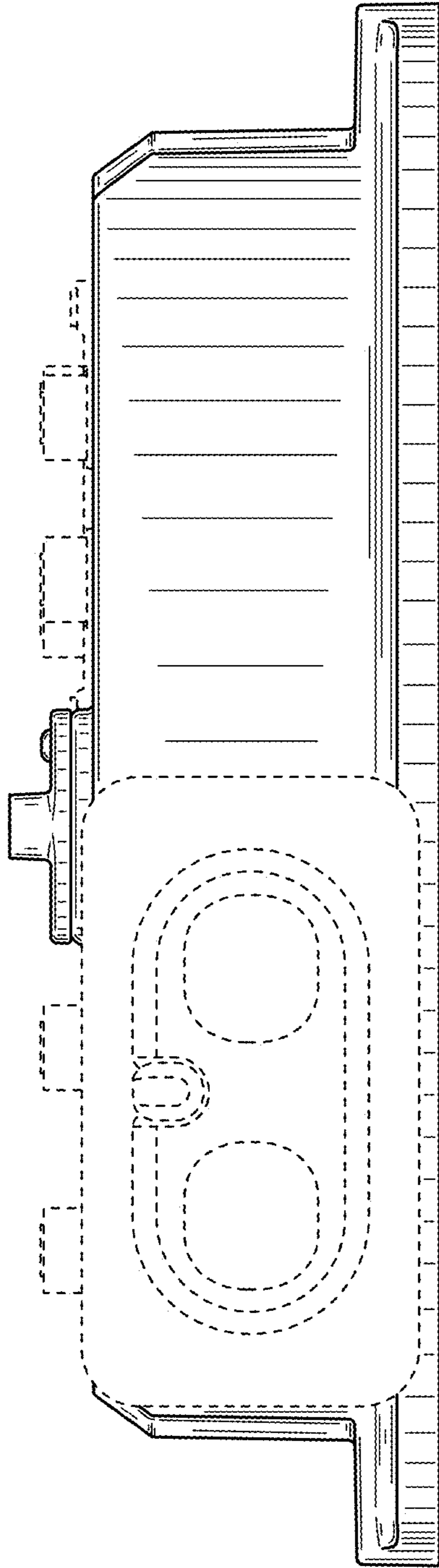


FIG. 4

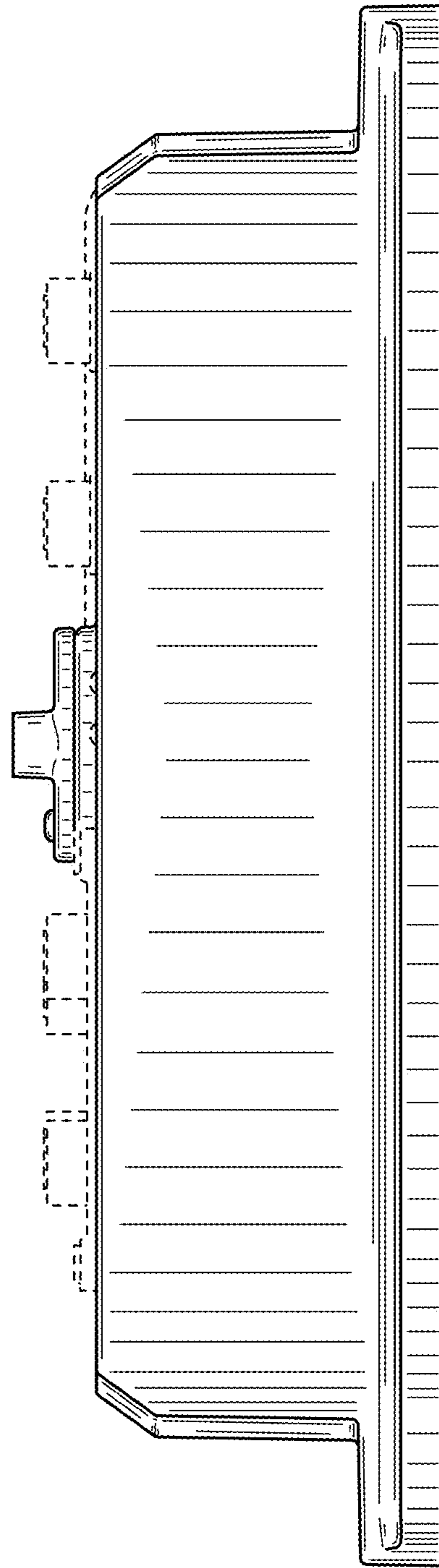


FIG. 5

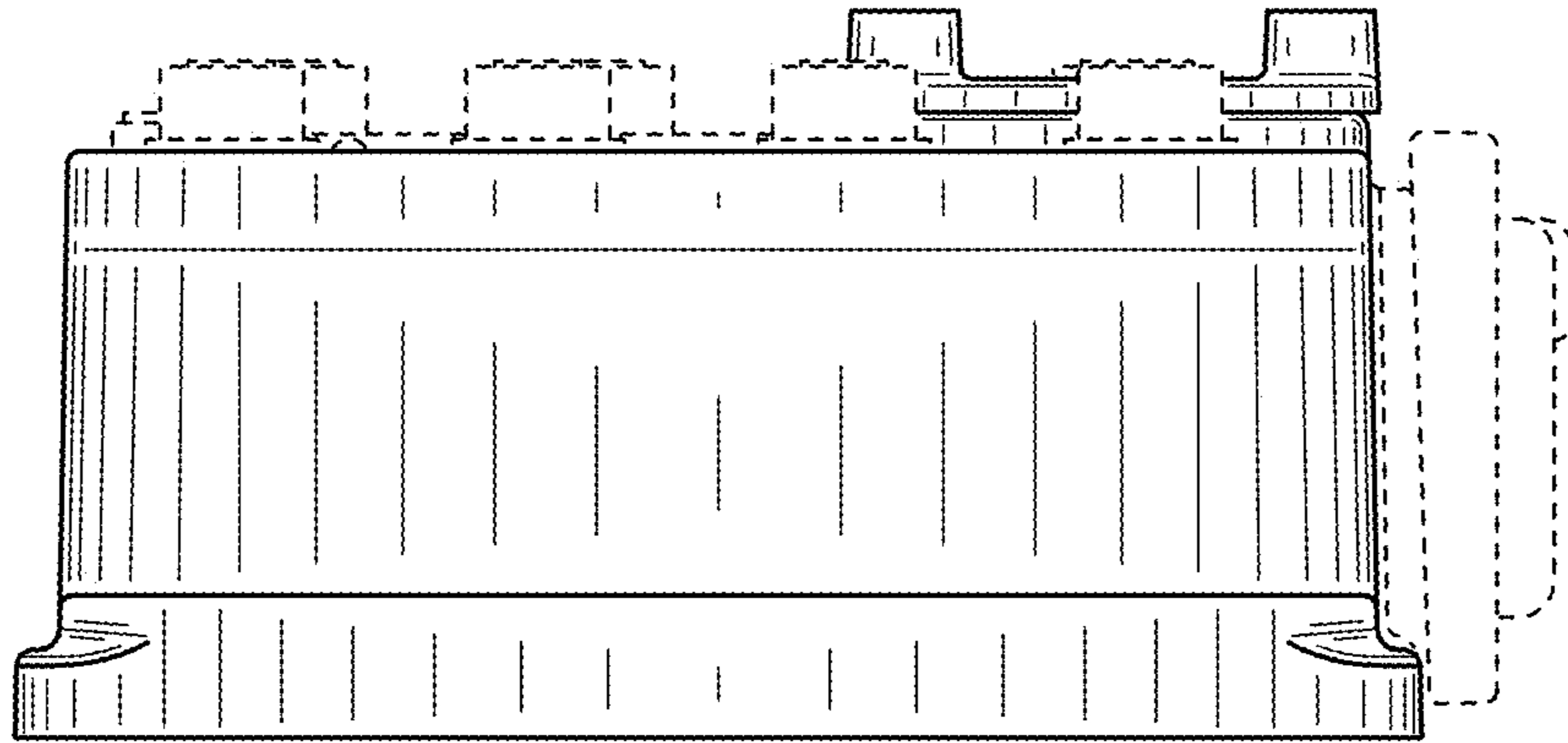


FIG. 6

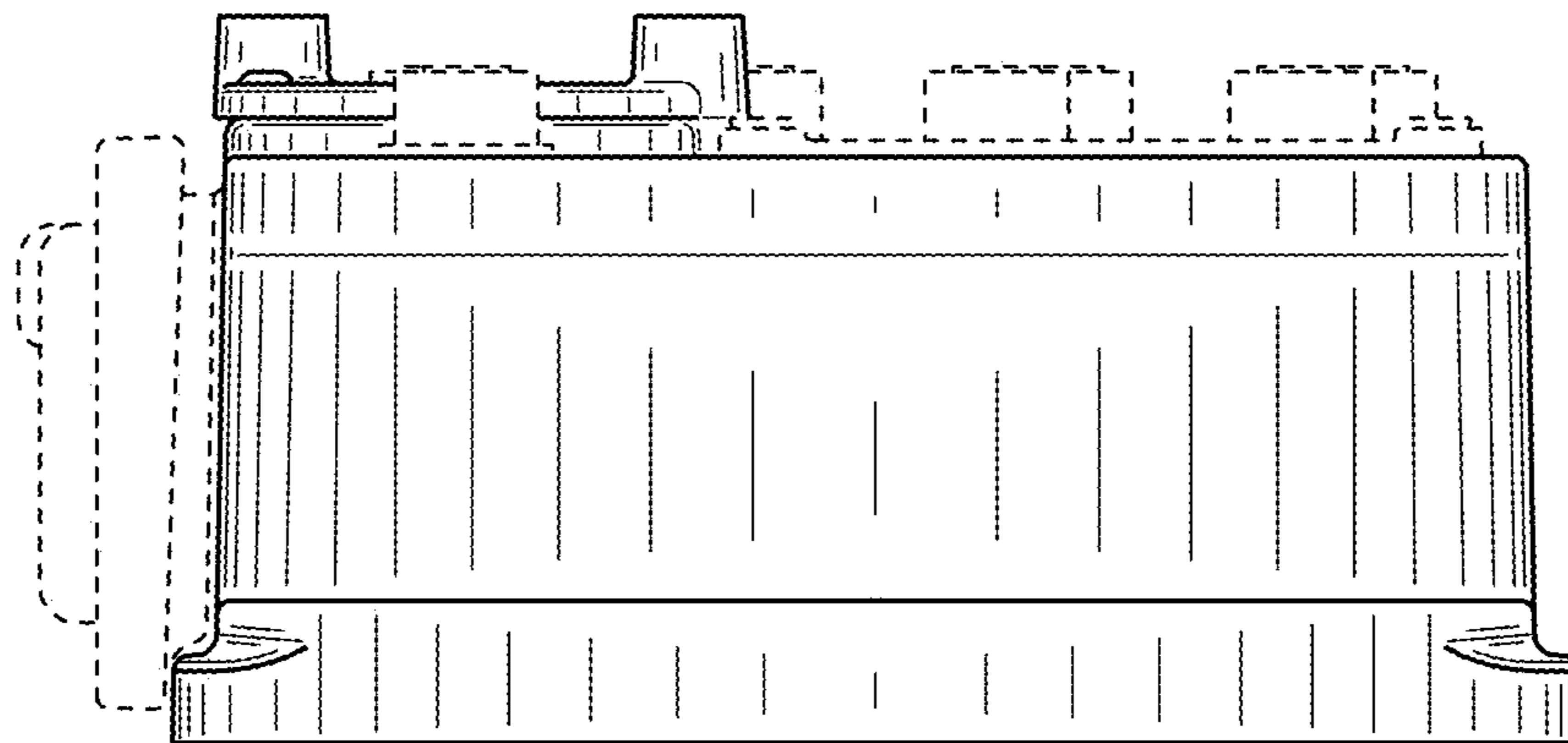


FIG. 7